

FEATURES

- Shrink pitch (1.778mm) sockets for high-density mounting.
- Dual wipe contact ensures high reliability.
- The small terminal end surface area (0.3 x 0.4) makes for easy PCB patterned routing.

SPECIFICATIONS

PERFORMANCE

Insulation Resistance	1,000M Ω min. at 500VDC				
Dielectric Withstanding Voltage	700VAC rms for 1 minute				
Contact Resistance	20m Ω max. at 10mA				
Current Rating	1A				
O- // T P	150°C max. continuous (IC7612)				
Operating Temperature Range	170°C max. continuous (IC7620)				

MATERIAL AND FINISH

Housing	PSF (glass-filled), UL94V-0 rated (IC7612)
Housing	PES (glass-filled), UL94V-0 rated (IC7620)
Contacts	Copper alloy, gold plating over nickel

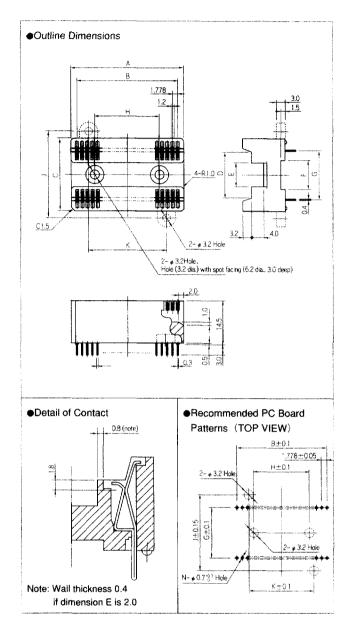
ORDERING CODE



MF = With
Flange option Unmarked = Without
Straight solder dip terminal
Type of contact plating G = Gold
Distance between IC terminal rows: 6 = 0.6 inches
Number of leads

Insulator 12 = PSF, 20 = PES

IC76 series



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IC76**2003G4 (MF)	20	20.0	16.002	17.0	8.3	2.0	7.5	11.4		23.0	11.0
IC76**-2006G4 (MF)	20	19.5	16.002	24.6	15.9	8.0	10.3	19.0	_	30.6	11.0
IC76 * *2203G4 (MF)	22	22.0	17.78	17.0	8.3	2.0	7,5	11.4	- -	23.0	11.0
1C76 * * 2403 G4 (MF)	24	24.0	19.558	17.0	8.3	2.0	7.5	11.4	4 -	23.0	13.0
IC76**-2804G4 (MF)	28	27.5	23.114	19.5	10.8	2.9	8.0	13.9		25.5	16.5
IC76**-3004-G4 (MF)	30	29.0	24.892	19.5	10.8	2.9	8.0	13.9		25.5	16.5
IC76 * *-4006G4 (MF)	40	36.0	33.782	24.6	15.9	8.0	10.3	19.0	25.5	30.6	25.5
IC76**-4206-G4 (MF)	42	39.5	35.56	24.6	15.9	8.0	10.3	19.0	25.5	30.6	25.5
IC76**-4806G4 (MF)	48	45.0	40.894	24.6	15.9	8.0	10.3	19.0	26.0	30.6	26.0
IC76**-5206-G4 (MF)	52	48.5	44.45	24.6	15.9	8.0	10.3	19.0	28.0	30.6	28.0
IC76 * * 64075 G4 (MF)	64	59.5	55.118	28.4	19.7	11.8	13.7	22.8	29.5	38.2	29.5

Unit = mm